

Attorney Docket No.: 00CON115P

In the Claims:**Claims 1-10 (canceled).****Claim 11 (currently amended):** A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a blind hole extending through said second layer of metal of said printed circuit board, said blind hole being adjacent to said die, said blind hole being filled with a mold compound, said blind hole being unplated, said mold compound surrounding and covering said die, wherein said mold compound is locked into said second layer of metal of said printed circuit board;

wherein said printed circuit board further comprises a layer of resin between said first and second layers of metal, wherein said blind hole extends through said layer of resin to form a structure with interlocking cracks and crevices within said layer of resin.

BEST AVAILABLE COPY

Attorney Docket No.: 00CON115P

Claims 12-13 (canceled).

Claim 14 (original): The structure of claim 11 further comprising a bond wire, wherein a first end of said bond wire is bonded to a die bonding pad on said die and a second end of said bond wire is bonded to a printed circuit board bonding location on said printed circuit board.

Claim 15 (original): The structure of claim 11 wherein said mold compound is selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin.

Claim 16 (original): The structure of claim 11 further comprising a layer of die attach between said die and said printed circuit board.

Claim 17 (canceled).

Claim 18 (previously presented): The structure of claim 11 further comprising a layer of die attach between said die and said second layer of metal.

Claim 19 (previously presented): The structure of claim 11 wherein said second layer of metal comprises gold-plated copper.

Attorney Docket No.: 00CON115P

Claim 20 (currently amended): A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a first portion of a mold compound surrounding and covering said die, said mold compound being selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said die, said through hole being completely filled with a second portion of said mold compound said through hole being unplated, wherein said second portion of said mold compound in said through hole locks said first portion of said mold compound into said printed circuit board;

wherein said printed circuit board further comprises a layer of resin between said first and second layers of metal, wherein said through hole extends through said layer of resin to form a structure with interlocking cracks and crevices within said layer of resin.

Attorney Docket No.: 00CON115P

Claim 21 (previously presented): The structure of claim 20 further comprising a bond wire, wherein a first end of said bond wire is bonded to a die bonding pad on said die and a second end of said bond wire is bonded to a printed circuit board bonding location on said printed circuit board.

Claim 22 (previously presented): The structure of claim 20 further comprising a layer of die attach between said die and said printed circuit board.

Claim 23 (previously presented): The structure of claim 20 further comprising a layer of die attach between said die and said second layer of metal.

Claim 24 (previously presented): The structure of claim 20 wherein said second layer of metal comprises gold-plated copper.

Claim 25 (currently amended): A plastic laminate-based molded printed circuit board package comprising:

a printed circuit board including a semiconductor die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

Attorney Docket No.: 00CON115P

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a first portion of a mold compound surrounding and covering said semiconductor die, said mold compound being selected from the group consisting of multifunctional epoxy, novolac, and biphenyl resin;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said semiconductor die, said through hole being completely filled with a second portion of said mold compound said through hole being unplated, wherein said second portion of said mold compound in said through hole locks said first portion of said mold compound into said printed circuit board;

wherein said printed circuit board further comprises a layer of resin between said first and second layers of metal, wherein said through hole extends through said layer of resin to form a structure with interlocking cracks and crevices within said layer of resin.

Claim 26 (previously presented): The structure of claim 25 further comprising a bond wire, wherein a first end of said bond wire is bonded to a semiconductor die bonding pad on said semiconductor die and a second end of said bond wire is bonded to a printed circuit board bonding location on said printed circuit board.

Attorney Docket No.: 00CON115P

Claim 27 (previously presented): The structure of claim 25 further comprising a layer of die attach between said semiconductor die and said printed circuit board.

Claim 28 (previously presented): The structure of claim 25 further comprising a layer of die attach between said die and said second layer of metal.

Claim 29 (previously presented): The structure of claim 25 wherein said second layer of metal comprises gold-plated copper.

**This Page is Inserted by IFW Indexing and Scanning
Operations and is not part of the Official Record**

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

- ☐ **BLACK BORDERS**
- ☐ **IMAGE CUT OFF AT TOP, BOTTOM OR SIDES**
- ☐ **FADED TEXT OR DRAWING**
- ☐ **BLURRED OR ILLEGIBLE TEXT OR DRAWING**
- ☐ **SKEWED/SLANTED IMAGES**
- ☐ **COLOR OR BLACK AND WHITE PHOTOGRAPHS**
- ☐ **GRAY SCALE DOCUMENTS**
- ☐ **LINES OR MARKS ON ORIGINAL DOCUMENT**
- ☐ **REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY**
- ☐ **OTHER:** _____

IMAGES ARE BEST AVAILABLE COPY.

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.